

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
QIANLI DI	06/25/2015
XIAOYUAN YU	06/25/2015
RECEIVING PARTY DATA	
Name:	VIA ALLIANCE SEMICONDUCTOR CO., LTD
Street Address:	ROOM 301, NO.2537, JINKE ROAD
Internal Address:	ZHANGJIANG HI-TECH PARK
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201203
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14882673
CORRESPONDENCE DATA	
Fax Number:	(719)623-0141
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	HUFFMAN LAW GROUP, P.C.
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Address Line 4:	COLORADO SPRINGS, COLORADO 80922
ATTORNEY DOCKET NUMBER:	VCPU15-0012
NAME OF SUBMITTER:	TAYSIE J. LOCKE
SIGNATURE:	/Taysie J. Locke/
DATE SIGNED:	10/14/2015
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
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**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE
ASSIGNEE**

TITLE OF INVENTION	MICROPROCESSOR WITH FUSED RESERVATION STATIONS STRUCTURE
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This is a combined declaration and assignment by the inventor(s) named below
to the assignee named below.

I. Declaration and Related Statements

As a below named inventor, I hereby declare that:

This declaration is directed to:

The attached application; or

United States application or PCT International application number _____
filed on _____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in
the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable
under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

II. Assignment

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), having
invented certain new and useful improvements as below entitled, for which application for
United States Letters Patent is made, the said application having been executed on even date
herewith;

AND WHEREAS, **VIA ALLIANCE SEMICONDUCTOR CO., LTD.** together with any successors, legal
representatives, or assigns thereof, with its principal office at **Room 301, No.2537, Jinke
Road, Zhangjiang Hi-Tech Park, Shanghai 201203, CHINA**, wants to acquire the entire right,
title and interest in and to the said invention(s), and to the said application and any Letters
Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby
acknowledged, I have sold, assigned, transferred and set over, and do hereby sell, assign,
transfer and set over to the said **VIA ALLIANCE SEMICONDUCTOR CO., LTD.**, its successors and
assigns, the entire right, title and interest in and to the said invention and in and to the said
application and all patents which may be granted thereon, and all divisions, reissues,
substitutions, continuations, and extensions thereof; and I/we hereby authorize and request
the Commissioner of Patents, and any officials of foreign countries whose duty it is to issue
patents on applications, to issue all patents for said invention, or patents resulting therefrom,
insofar as my interest in concerned, to the said **VIA ALLIANCE SEMICONDUCTOR CO., LTD.** as
assignee of my entire right, title and interest;

I ALSO HEREBY sell and assign to **VIA ALLIANCE SEMICONDUCTOR CO., LTD.**, its successors and
assigns, my foreign rights to the invention disclosed in said application, in all countries of the
world, including the right to file applications and obtain patents under the terms of the
International Convention for the Protection of Industrial Property, and of the European Patent
Convention, and further agree to execute any and all patent applications, assignments,

affidavits, and any other papers in connection therewith necessary to perfect such patent rights;

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant that I will communicate to said VIA ALLIANCE SEMICONDUCTOR CO., LTD., or to its successors, assigns and legal representatives, any facts known to me respecting said invention, and at the expense of said VIA ALLIANCE SEMICONDUCTOR CO., LTD., testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said VIA ALLIANCE SEMICONDUCTOR CO., LTD., its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

III. Signatures

A. Inventors

Signature: QIANLI DI	Date: 06/25/15
QIANLI DI	

Signature: XIAOYUAN YU	Date: 06/25/15
XIAOYUAN YU	

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